

# How to get published with the IEEE

Lukács Eszter

Client Services Manager Europe

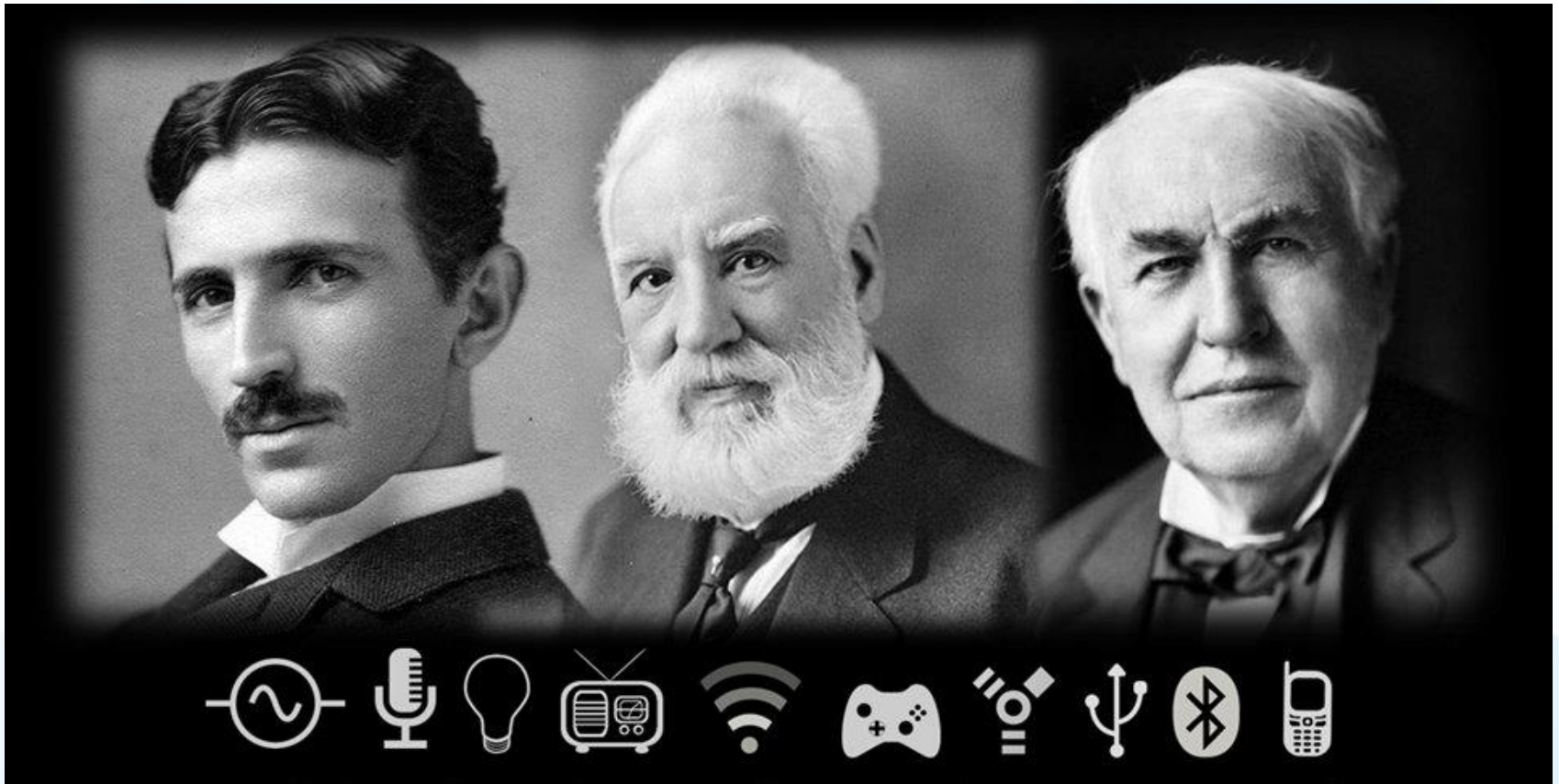


**ČVUT**

**IEEE Xplore<sup>®</sup>**  
*Digital Library*



# 1884: Where we came from



# About the IEEE

- World's largest technical membership association with more than 430,000 members in over 160 countries
- Not for profit organization “Advancing Technology For Humanity”
- Four Core areas of activity
  - Membership organization
  - Conferences organizer
  - Standards developer
  - Publisher of journals, conferences, standards, ebooks and elearning
- IEEE *Xplore* by the numbers:
  - Nearly 4 million total documents
  - Over 3 million unique users
  - More than 8 million downloads per month
  - 15 year anniversary in 2015!



IEEE student volunteers in Mumbai



IEEE Day Contest Winner, Colombia

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# Why you should rely on IEEE information

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# Full text access to IEEE/IET Electronic Library (IEL)

- Nearly four million full text documents
- 179 **IEEE journals & magazines**
- 1400+ annual **IEEE conferences** + 43 **VDE conferences**
- More than **2800 IEEE standards** (active, archived, redlines) + **IEEE Standard Dictionary**
- 20 **IET conferences**, 26 **IET journals & magazines**
- **Bell Labs Technical Journal (BLTJ)** back to 1922
- Backfile to 1988, select legacy data back to 1872
- Inspec index records for all articles

# IEEE quality makes an impact

Thomson Reuters Journal Citation Reports® by Impact Factor

## IEEE publishes:

**17 of the top 20** journals in Electrical and Electronic Engineering

**14 of the top 15** journals in Telecommunications

**3 of the top 5** journals in Computer Science, Hardware & Architecture

**3 of the top 5** journals in Computer Science, Cybernetics

**3 of the top 5** journals in Automation & Control Systems

**3 of the top 5** journals in Artificial Intelligence

**2 of the top 5** journals in Imaging Science & Photographic Technology

The Thomson Reuters Journal Citation Reports presents quantifiable statistical data that provides a systematic, objective way to evaluate the world's leading journals.

Based on the 2015 study released June 2016

More info: [www.ieee.org/citations](http://www.ieee.org/citations)

# IEEE quality makes an impact

Thomson Reuters Journal Citation Reports® by Impact Factor

## IEEE journals are:

- # 1 in Automation and Control
- # 1 in Artificial Intelligence
- # 1 in Computer Hardware
- # 1 in Cybernetics
- # 1 in Information Systems
- # 1 in Manufacturing Engineering
- # 1 in Theory and Methods
- # 1 in Telecommunications
- # 2 in Electrical Engineering
- # 3 in Aerospace Engineering



The Thomson Reuters Journal Citation Reports presents quantifiable statistical data that provides a systematic, objective way to evaluate the world's leading journals.

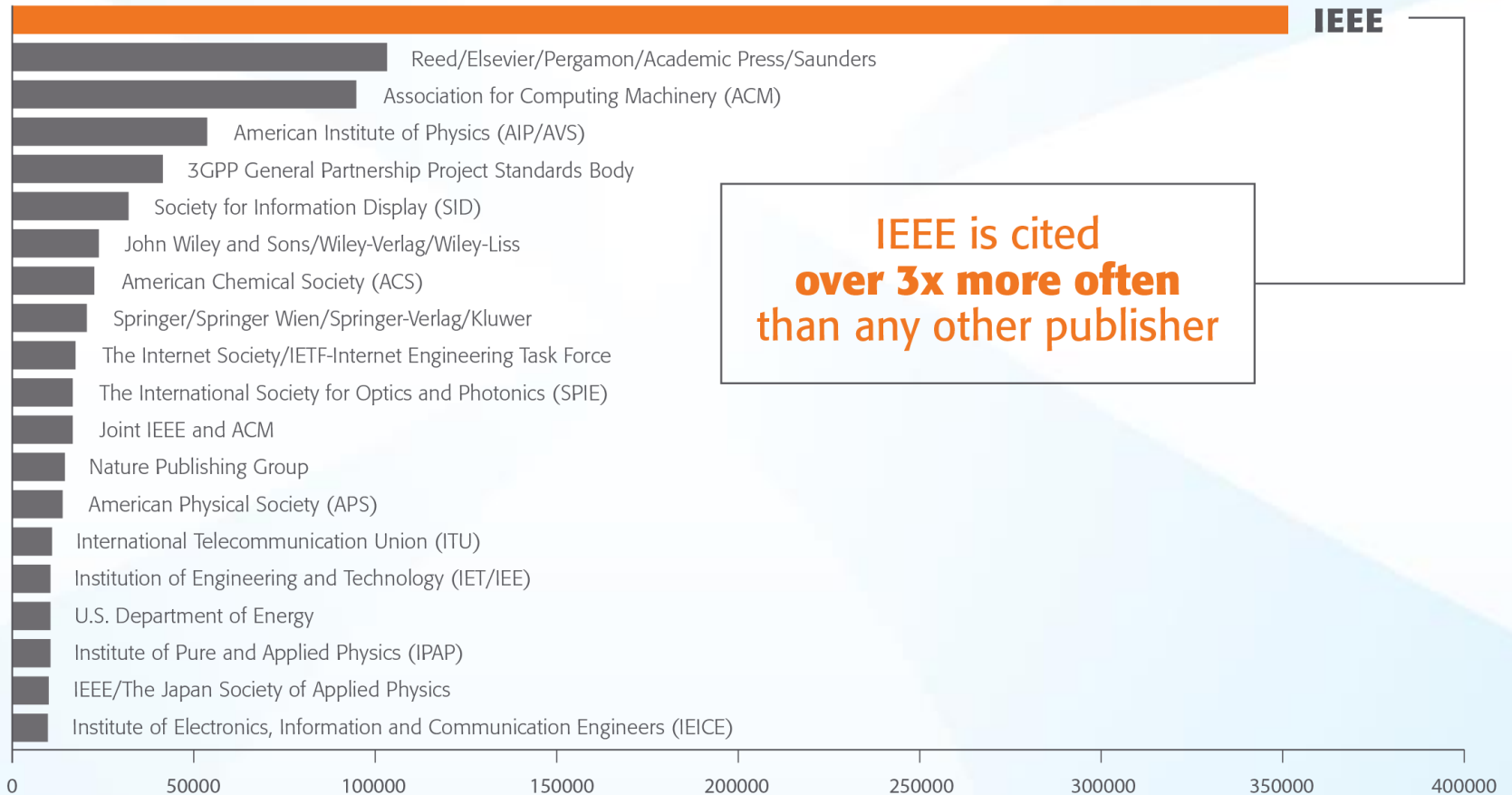
Based on the 2015 study released June 2016

# IEEE and Patents



# IEEE Leads US Patent Citations

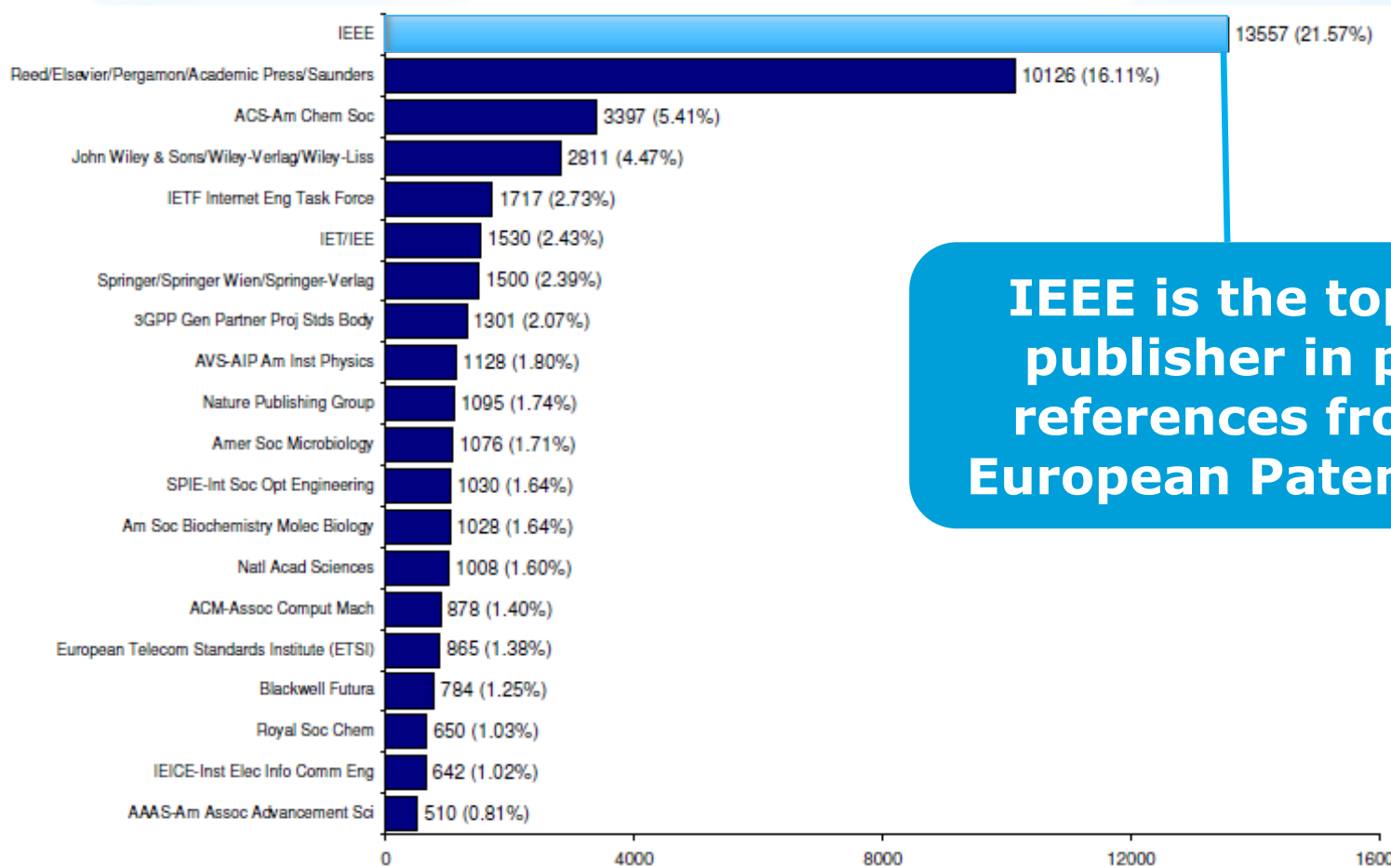
## Top 20 Publishers Referenced Most Frequently by Top 40 Patenting Organizations



Source: 1790 Analytics LLC 2015. Based on number of references to papers/standards/conferences from 1997-2014

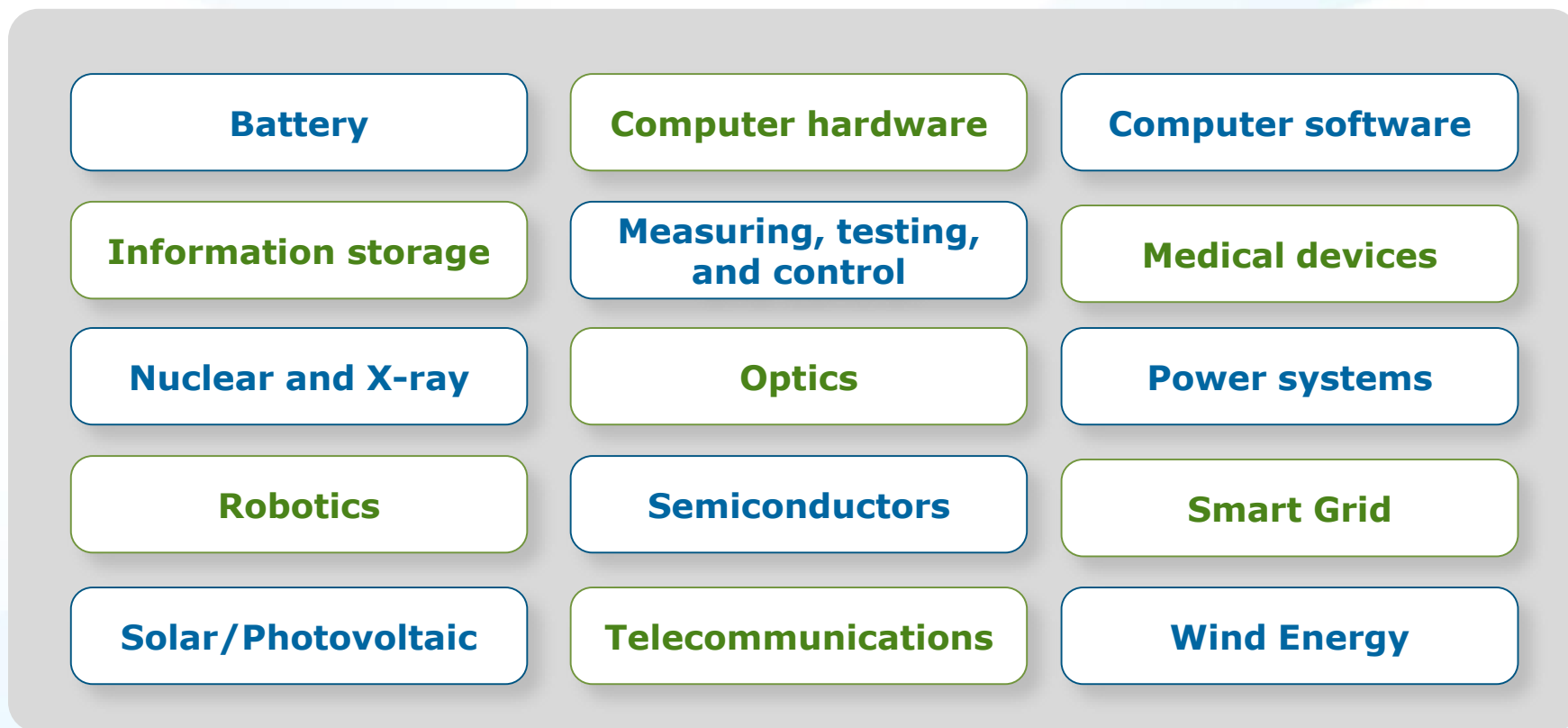
# IEEE Leads European Patent Citations

## Top 20 Publishers Referenced Most Frequently by Top 25 Patenting Organizations



**IEEE is the top cited publisher in patent references from the European Patent Office**

# Technology areas where patents cite IEEE most



Source: 1790 Analytics LLC 2015

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# Content on IEEE Xplore Digital Library

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# Full text content from all 39 IEEE Societies

**IEEE Aerospace and Electronic Systems Society**

**IEEE Antennas and Propagation Society**

**IEEE Broadcast Technology Society**

**IEEE Circuits and Systems Society**

**IEEE Communications Society**

**IEEE Components, Packaging, and Manufacturing Technology Society**

**IEEE Computational Intelligence Society**

**IEEE Computer Society**

**IEEE Consumer Electronics Society**

**IEEE Control Systems Society**

**IEEE Dielectrics and Electrical Insulation Society**

**IEEE Education Society**

**IEEE Electron Devices Society**

**IEEE Electromagnetic Compatibility Society**

**IEEE Engineering in Medicine and Biology Society**

**IEEE Geoscience and Remote Sensing Society**

**IEEE Industrial Electronics Society**

**IEEE Industry Applications Society**

**IEEE Information Theory Society**

**IEEE Instrumentation and Measurement Society**

**IEEE Intelligent Transportation Systems Society**

**IEEE Magnetics Society**

**IEEE Microwave Theory and Techniques Society**

**IEEE Nuclear and Plasma Sciences Society**

**IEEE Oceanic Engineering Society**

**IEEE Photonics Society**

**IEEE Power Electronics Society**

**IEEE Power & Energy Society**

**IEEE Product Safety Engineering Society**

**IEEE Professional Communications Society**

**IEEE Reliability Society**

**IEEE Robotics and Automation Society**

**IEEE Signal Processing Society**

**IEEE Society on Social Implications of Technology**

**IEEE Solid-State Circuits Society**

**IEEE Systems, Man, and Cybernetics Society**

**IEEE Technology and Engineering Management Society NEW in 2015**

**IEEE Ultrasonics, Ferroelectrics, and Frequency Control Society**

**IEEE Vehicular Technology Society**

# IEEE covers all areas of technology

More than just electrical engineering & computer science

MACHINE LEARNING **BIG DATA**

**OPTICS** RENEWABLE ENERGY

SEMICONDUCTORS **SMART GRID**

**IMAGING** NANOTECHNOLOGY

SIGNAL PROCESSING **AEROSPACE**

**COMMUNICATIONS** HUMAN-CENTERED INFORMATICS

BIOMEDICAL ENGINEERING **ELECTRONICS**

**NEXT GEN WIRELESS** CIRCUITS

**CLOUD COMPUTING**

**CYBER SECURITY** ELECTROMAGNETICS  **IEEE**

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# Multidisciplinary Content on IEEE Xplore Digital Library

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# Life Sciences

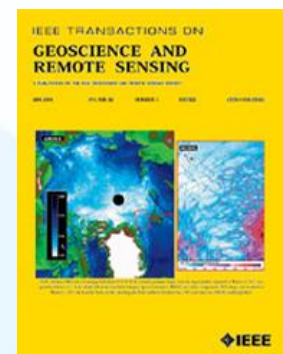
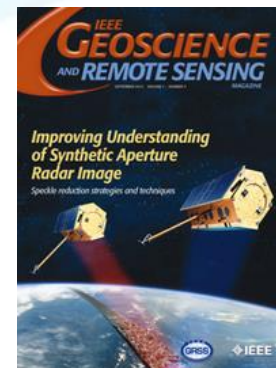
- At least **eight IEEE publications** are dedicated in whole or in part to technology related to Life Sciences.
- Plus, there are more than 90 annual conferences, 20 periodicals and 20 IEEE standards that cover **medical device communications**.
- In IEEE *Xplore*, you'll also find coverage of therapeutic devices used in rehabilitation processes, such as physical therapy and devices used to restore movement and function.
- Examples of IEEE publications:
  - **IEEE Pulse**
  - **IEEE Trans. on Biomedical Engineering**
  - **IEEE Reviews on Biomedical Engineering**
  - **IEEE Trans. on Neural Systems and Rehabilitation Engineering**
  - **IEEE Trans. on Information Technology in Biomedicine**
  - **IEEE Trans. on Medical Imaging**
  - **IEEE/ACM Trans. on Computational Biology and Bioinformatics**
  - **IEEE Trans. on Biomedical Circuits and Systems**
  - **IEEE Trans. on NanoBioscience**
  - **IEEE Trans. on Autonomous Mental Development.**





# Geoscience and related fields

- IEEE's geoscience and remote sensing publications cover the fusion of engineering and **geoscientific fields including geophysics, geology, hydrology, meteorology, etc.**
- In IEEE *Xplore*, you'll also find information relevant to **natural resources engineering and mineral resources engineering**, including extensive coverage of technologies related to **oil and gas exploration, drilling operations, offshore oil rigs and mining.**
- Examples of IEEE publications:
  - **IEEE Trans. on Geoscience & Remote Sensing**
  - **IEEE Geoscience & Remote Sensing Magazine**
  - **IEEE Geoscience & Remote Sensing Letters**
  - **IEEE International Symposium Geoscience and Remote Sensing (IGARSS)**
  - **IEEE Petroleum and Chemical Industry Technical Conference (PCIC)**



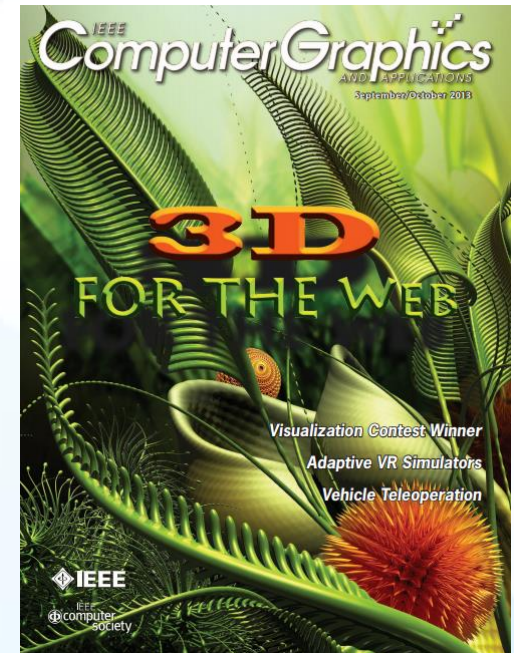
# Manufacturing Engineering

- IEEE's publications cover manufacturing practices and technologies, including **the development of systems, processes, machines, and tools.**
- In IEEE *Xplore*, you'll find information on **virtual manufacturing, computer integrated manufacturing, agile manufacturing, quality control, robotics and automation, mechatronics,** and much more
- Relevant IEEE publications include:
  - IEEE/ASME Transactions on Mechatronics (#1 most cited journal in Engineering - Manufacturing)
  - IEEE Transactions on Components, Packaging and Manufacturing Technology
  - IEEE Transactions on Semiconductor Manufacturing
  - IEEE Transactions on Automation Science and Engineering
  - IEEE Robotics & Automation Magazine
  - IEEE International Symposium on Assembly and Manufacturing
  - International Conference on Digital Manufacturing and Automation
  - e-Manufacturing & Design Collaboration Symposium Electronics Manufacturing Technology Symposium
  - International Conference on System Science, Engineering Design and Manufacturing Informatization



# Digital Art & Technology

- IEEE *Xplore* covers the leading edge of **computer graphics technology and its applications** in everything from business to the arts.
- Topics include **computer graphics, design, animation, 3D, user interface, motion graphics**, and more
- Examples of IEEE *Xplore* publications:
  - IEEE Computer Graphics
  - IEEE Trans. On Visualization & Computer Graphics
  - International Conference on Computer-Aided Design & Computer Graphics
  - International Conference on Computer Graphics, Imaging & Visualization
  - International Conference on Image & Graphics



# Game Design

- IEEE *Xplore* covers the design of **video games, mathematical games, human-computer interactions in games, and games involving physical objects.**
- Topics include **game production, computational intelligence, artificial intelligence, simulations,** and more
- Examples of IEEE *Xplore* publications:
  - IEEE Trans. On Computational Intelligence and AI in Games
  - Symposium on Computational Intelligence in Games
  - International Conference on Computer Games
  - International Workshop on Digital Game and Intelligent Toy Enhanced Learning
  - International Symposium on Haptic, Audio, Visual Environments and Games

Computational Intelligence in Games 2014  
August 26 – 29, Park Inn Hotel, Dortmund, Germany

www.cig2014.de April 1, 2014 IEEE Explore

Mark Rieffl  
Georgia Institute of Technology

Jochen Peckert  
Blue Byte Games

Rilla Khaled  
University of Malta

Thorsten Quandt  
Witten Institute Münster

Computational & artificial intelligence in:  
• Video games  
• Board and card games  
• Economic or mathematical games  
• Serious games  
• Augmented and mixed-reality games  
• Games for mobile platforms

Calls for Special Sessions (March 1) and Tutorials (April 1) OPEN!

Learning in games  
• Procedural content generation  
• Player/opponent modeling in games  
• Player affective modeling  
• Player satisfaction and experience in games  
• Computational and artificial intelligence based game design  
• Intelligent interactive narrative  
• Theoretical or experimental analysis of AI techniques for games  
• Non-player characters in games  
• Comparative studies and game-based benchmarking  
• Applications of game theory

ERCIS

General Chairs: Günter Rüdolph, TU Dortmund, Germany  
Mike Preuss, WWU Münster, Germany  
Program Chairs: Muzam Eladhari, University of Malta  
Moshe Sipper, Ben-Gurion University of the Negev, Israel  
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Proceedings Chair: Paolo Burelli, Aalborg University, Copenhagen, Denmark

IEEE IEEE Computational Intelligence Society

# With IEEE *Xplore*, learn how technology impacts fields such as...

**Healthcare:** telemedicine, electronic medical records, patient-specific healthcare, cloud computing in the medical field, patient monitoring systems, informatics, and more

## Emerging Technologies for Patient-Specific Healthcare

### I. INTRODUCTION

**P**ATIENT-SPECIFIC healthcare is a research field that has recently garnered much more attention due to the benefits of better services provided to patients and a reduction of healthcare costs. A series of emerging technologies [1] aim to emphasize the provision of personalized healthcare services to patients [2]–[5]. These include the following.

- 1) Pattern recognition methods for signal pattern classification toward the prediction and diagnosis of diseases.
- 2) Body sensor networks.
- 3) Algorithms for the analysis of patient-specific physiological signals.
- 4) Ontologies and context-based electronic health records (EHRs).
- 5) Methodologies for the integration of clinical journals and

intranuclear spike activity recorded from Parkinson's disease patients.

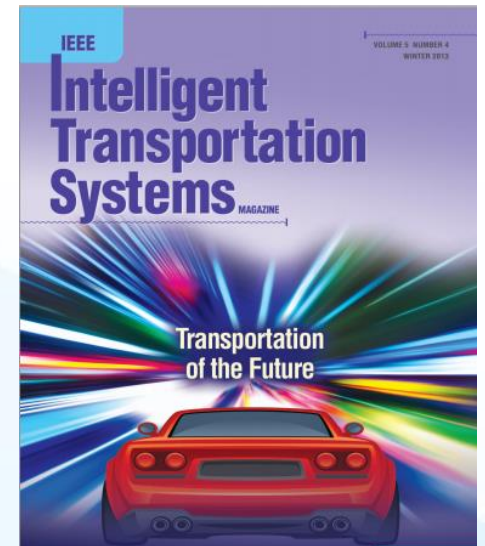
A new Neural Sensing Healthcare System for 3D Vision Technology, NeuroGlasses, is presented in [7]. NeuroGlasses is a noninvasive, wearable physiological signal monitoring system to facilitate health analysis and diagnosis of 3-D video watchers. The NeuroGlasses system acquires health-related signals by physiological sensors and provides feedback of health-related features. The system employs signal-specific reconstruction and features extraction to compensate the distortion of signals caused by the variation of sensor placement. Through an on-campus pilot study, the experimental results show that NeuroGlasses system can effectively provide physiological information.

In [8], the authors explore how the rhythmogram can be used

# With IEEE *Xplore*, learn how technology impacts fields such as...

**Transportation:** intelligent transportation systems, logistics, supply chain management, and more

- Related IEEE Journals & Conferences:
  - IEEE Trans. on Intelligent Transportation Systems
  - IEEE Intelligent Transportation Systems Magazine
  - IEEE Trans. on Automation Science and Engineering
  - IEEE International Conference on Automation and Logistics



# With IEEE *Xplore*, learn how technology impacts fields such as...

**Entertainment:** computer graphics, animation, 3D, digital motion pictures, laser projectors, and more

## Bringing Physical Characters to Life

Akhil J. Madhani  
Walt Disney Imagineering R&D

### Ray Tracing for the Movie 'Cars'

Per H. Christensen\*    Julian Fong    David M. Laur    Dana Batali

Pixar Animation Studios



#### Abstract

At Disney, we are s  
to present these ch  
entertainment robot  
Disney in attraction

In this talk, I hope  
Disney. In particul  
distilled from Disne

As examples of cha  
I discuss two newer  
the Disney theme  
developed in conjur  
and has made app

#### ABSTRACT

This paper describes how we extended Pixar's RenderMan renderer with ray tracing abilities. In order to ray trace highly complex scenes we use multiresolution geometry and texture caches, and use ray differentials to determine the appropriate resolution. With this method we are able to efficiently ray trace scenes with much more geometry and texture data than there is main memory. Movie-quality rendering of scenes of such complexity had only previously been possible with pure scanline rendering algorithms. Adding ray

texture cache keeps recently accessed texture tiles ready for fast access. This combination of ray differentials and caching makes ray tracing of very complex scenes feasible.

This paper first gives a more detailed motivation for the use of ray tracing in 'Cars', and lists the harsh rendering requirements in the movie industry. It then gives an overview of how the REYES algorithm deals with complex scenes and goes on to explain our work on efficient ray tracing of equally complex scenes. An explanation of our hybrid rendering approach, combining REYES with ray tracing, follows. Finally, we measure the efficiency of our method on a



# With IEEE *Xplore*, learn how technology impacts fields such as...

**Apparel Design:** e-textiles, smart fabrics, intelligent clothing, wearable computing, and more



## Wearable Computing

Editor: Bernt Schiele ■ MPI Informatics ■ [schiele@mpi-inf.mpg.de](mailto:schiele@mpi-inf.mpg.de)

### Smart Textiles: From Niche to Mainstream

*Jingyuan Cheng, Paul Lukowicz, Niels Henze, Albrecht Schmidt,  
Oliver Amft, Giovanni A. Salvatore, and Gerhard Tröster*

**A**s with many new technologies, smart clothing and textile electronics currently suffer from the chicken-and-egg problem—that is, for the devices to be widely deployed, the price must come down, but for the price to come down, the devices must be mass-produced (and widely deployed).

between the various people creating the fabric, garments, electronics platforms, and apps (see Figure 1).

The solution to the chicken-and-egg problem must incorporate all steps—from garment production through to wearable sensing apps. With appropriate abstraction, the solution in

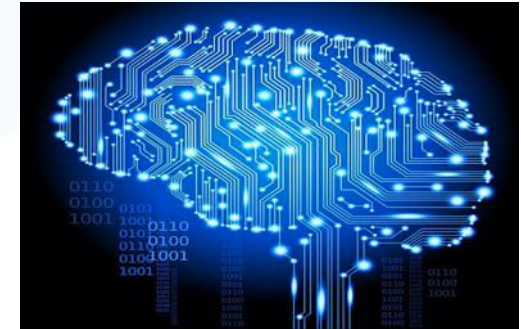
process should essentially remain a series of cutting and sewing steps, possibly including the integration of different materials. Designers could apply this process to the sensing layer, as well, to align the sensors with the garment and with targeted application domains. However, three requireme



# New IEEE Journals Planned for 2017

In 2017, IEEE will introduce six new journals that will be available for subscription:

- *IEEE **Communications Standards Magazine***
- *IEEE Journal of **Electromagnetics, RF and Microwaves in Medicine and Biology***
- *IEEE Transactions on **Emerging Topics in Computational Intelligence***
- *IEEE Transactions on **Green Communications and Networking***
- *IEEE Transactions on **Radiation and Plasma Medical Sciences***
- *IEEE Journal of **Radio Frequency Identification***



– All Included in an IEL Subscription

For a complete title listing, to go: <http://ieeexplore.ieee.org/xpl/opacjrn.jsp>

# New IEEE Journals Coming in 2016

In 2016, IEEE will introduce four new journals that will be available for subscription:

- *IEEE Transactions on **Intelligent Vehicles***
- *IEEE Journal on **Multiscale and Multiphysics Computational Techniques***
- *IEEE **Robotics and Automation Letters***
- *IEEE Transactions on **Sustainable Computing***



All included in an IEL subscription

For a complete title listing, to go: <http://ieeexplore.ieee.org/xpl/opacjrn.jsp>

# New IEEE Journals from 2015

- *IEEE Trans. on **Big Data***
- *IEEE Trans. on **Transportation Electrification***
- *IEEE Trans. on **Cognitive Communications and Networking***
- *IEEE Trans. on **Computational Imaging***
- *IEEE Trans. on **Molecular, Biological, and Multi-Scale Communications***
- *IEEE Trans. on **Multi-Scale Computing Systems***
- *IEEE Trans. on **Signal and Information Processing over Networks***
- *IEEE **Systems, Man, and Cybernetics** Magazine*

All included in an IEL subscription

For a complete title listing, to go: <http://ieeexplore.ieee.org/xpl/opacjrn.jsp>



# A sampling of some of the new conferences added in 2015

- **Big Data Software Engineering** (BIGDSE), 2015 IEEE/ACM 1st International Workshop on
- **Computational Electromagnetics** (ICCEM), 2015 IEEE International Conference on
- **DC Microgrids** (ICDCM), 2015 IEEE First International Conference on
- **Electromagnetic Compatibility and Signal Integrity**, 2015 IEEE Symposium on
- **Identity, Security and Behavior Analysis (ISBA)**, 2015 IEEE International Conference on
- **Industrial Engineering and Operations Management** (IEOM), 2015 International Conference on
- **Microwaves for Intelligent Mobility** (ICMIM), 2015 IEEE MTT-S International Conference on
- **Multimedia Big Data** (BigMM), 2015 IEEE International Conference on
- **Networking Systems and Security** (NSysS), 2015 International Conference on
- **Sampling Theory and Applications** (SampTA), 2015 International Conference on
- **Signal Processing, Informatics, Communication and Energy Systems** (SPICES), 2015 IEEE International Conference on
- **Smart Cities Conference** (ISC2), 2015 IEEE First International

# Examples of New IEEE Conferences in 2014



- **Internet of Things** (WF-IoT), 2014 IEEE World Forum on
- **Humanitarian Technology** Conference, (IHTC), 2014 IEEE Canada International
- **Aerospace Electronics and Remote Sensing Technology** (ICARES), 2014 IEEE International Conference on
- **Antenna Measurements & Applications** (CAMA), 2014 IEEE Conference on
- **Consumer Electronics**, Taiwan (ICCE-TW), 2014 IEEE International Conference on
- **Energy Conversion** (CENCON), 2014 IEEE Conference on
- **Ethics in Science**, Technology and Engineering, 2014 IEEE International Symposium on
- **Transportation Electrification** Asia-Pacific (ITEC Asia-Pacific), 2014 IEEE Conference and Expo
- **Intelligent Energy** and Power Systems (IEPS), 2014 IEEE International Conference on
- **Quantum Optics Workshop** (QOW), 2014
- **Sensor Systems for a Changing Ocean** (SSCO), 2014 IEEE
- **Wireless and Mobile**, 2014 IEEE Asia Pacific Conference on
- **Industrial Engineering and Information Technology** (IEIT), 2014 International Conference on
- **Guidance, Navigation and Control Conference** (CGNCC), 2014 IEEE Chinese

# Popular IEEE Standards

**IEEE 802 Series**—IEEE Standard for Ethernet

**IEEE 3000 Standards Collection™**—Formerly the IEEE Color Books®, this collection will reorganize the 13 Color Books into approximately 70 “dot” standards covering specific technical topics on all facets of industrial and commercial power systems.

**IEEE 81-2012™**—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System

**2012 National Electrical Safety Code® (NESC®)**—Sets the ground rules for practical safeguarding of persons during the installation, operation, or maintenance of electric supply and communications lines and associated equipment.

**IEEE 43™**—IEEE Recommended Practice for Testing Insulation Resistance of Electric Machinery

**IEEE 80™**—IEEE Guide for Safety in AC Substation Grounding

**IEEE 81™**—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System

# Enhancing the User Experience: Redesign of Full-Text HTML Articles

- More prominent
  - article metrics
  - related articles
  - featured media
- Author's ORCID identifier & bio
- Metrics gallery
- Multimedia gallery

The screenshot displays the IEEE Xplore Digital Library interface for a full-text HTML article. The page features a blue header with the IEEE Xplore logo and navigation links. A search bar is prominently placed below the header. The article title is "Article Title: Lorem Ipsum Dolor Sit Amet Sed Faucibus Augue Metus et Tempor Purus...". Below the title, there are three metrics boxes: "5 Cited in Papers", "4 Cited in Patents", and "9 Full Text Views". An orange arrow points from the search bar area down to the "Related Articles" section, which contains three article thumbnails. Another orange arrow points from the metrics boxes to the left. Below the metrics, there are author names with ORCID icons. The article content is displayed in a tabbed format, with the "Abstract" tab selected. The abstract text is "This space is reserved for impact message. In viverra tellus eu tellus congue molestie. Suspendisse porttitor dapibus consequat." An orange arrow points from the abstract text to the "Media Title / Information" section, which features a video player with a play button icon. The video player is set against a background of light trails. Below the video player, there is a note: "This space is reserved for graphical abstract text if and when available. Truncate and use ellipses if text exceeds three lines. View more expands text."

# NEW! Full-Text HTML for Standards

- Modern, mobile-friendly design
- Figures carousel
- Table of contents within Standard
- Search within a Standard
- Evolution of the Standard

The screenshot displays the IEEE Xplore Digital Library interface. At the top, there is a navigation bar with the IEEE Xplore logo, an Institutional Sign In button, and a search bar. Below the search bar, there are tabs for Basic Search, Author Search, and Publication Search, along with links for Advanced Search and Other Search Options. The main content area features the title "IEEE 18 - 2004 IEEE Standard for Shunt Power Capacitors" and its revision information. A carousel of figures is shown, including a diagram of a capacitor structure (Fig. 1), two graphs of capacitance vs. frequency (Fig. 2), and four graphs of loss tangent vs. frequency (Fig. 3). The interface also includes a Table of Contents section, a Download PDF button, and a list of actions like Download Citations, Email, Print, Request Permissions, and Share. The introduction text is visible at the bottom, starting with "Lorem ipsum dolor sit amet, consectetur adipiscing elit. Nullam dictum, tortor vel fringilla scelerisque, odio erat iaculis eros, quis ornare uma dui vel nisi. Suspendisse sollicitudin eros sed pharetra vestibulum. Fusce maximus ullamcorper orci, accumsan pulvinar dui tempor non. Quisque faucibus lectus eget enim sagittis, in auctor arcu viverra. Quisque molestie lacus eget sapien egestas, vitae efficitur turpis ullamcorper. Cras sit amet euismod mi. In viverra tellus eu tellus congue molestie. Suspendisse porttitor dapibus consequat. Nulla facilisi. In feugiat, neque nec egestas porttitor, nibh lorem elementum metus, sed dictum magna ante eu turpis. Aliquam rhoncus dolor vel eros porttitor, eu consectetur ante porta. Mauris ac malesuada lectus, sit amet volutpat ipsum. Cras dui ex, sagittis nec maximus ac, ..."



# What are standards?

- Standards are published documents that establish **specifications and procedures designed to ensure the reliability of the materials, products, methods, and/or services people use every day.**
- Standards form the fundamental building blocks **for product development** by establishing **consistent protocols** that can be universally understood and adopted
  - Standards establish compatibility, interconnectivity, interoperability, simplify product development, and speed time-to-market
- Standards make it easier to understand and compare competing products.
- As standards are **globally adopted** and applied in many markets, they also help with international trade

# Types of IEEE standards

- **Standards:** Documents with mandatory requirements.
- **Recommended Practices:** Documents in which procedures and positions preferred by the IEEE are presented.
- **Guides:** Documents in which alternative approaches to good practice are suggested but no clear-cut recommendations are made.
- **Trial-Use Documents:** Publications in effect for not more than two years.
  - Can be any of the categories of standards publications listed above.



# IEEE Standards Development Lifecycle

IEEE Standards are developed using a time-tested, effective and trusted process.



# States of Activity of IEEE standards



# IEEE Standards Development

IEEE standards development process may result in one or more of the following documents:

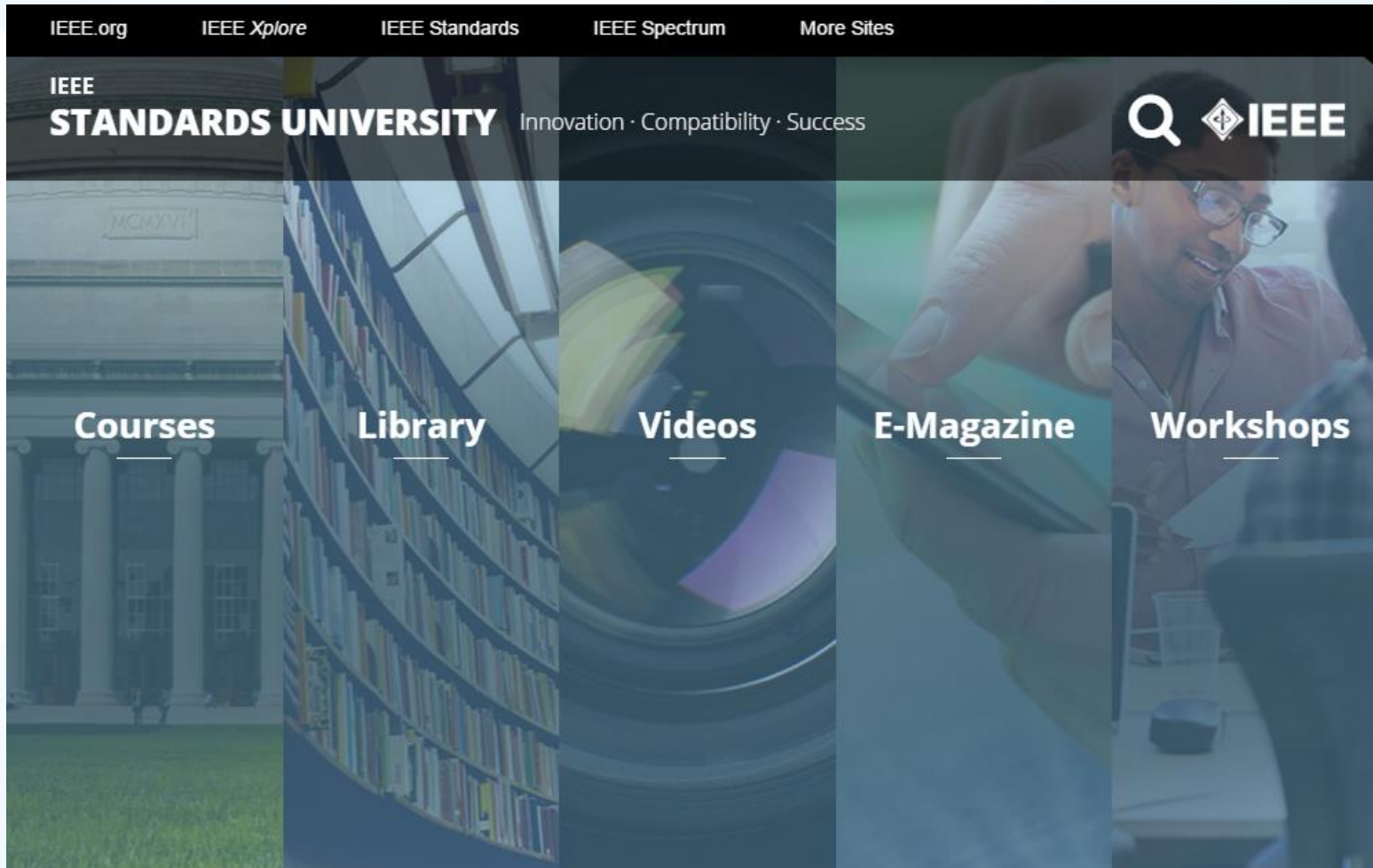
- **New:** Document that does not replace or modify another standard.
- **Revision:** Document that updates and replaces (i.e., supersedes) an existing IEEE standard in its entirety.
- **Amendment:** Document that adds to, removes from, or alters material in a portion of an existing IEEE standard and may make editorial or technical corrections to that standard.
- **Corrigendum:** Document that only corrects editorial errors, technical errors, or ambiguities in an existing IEEE standard. A corrigendum does not introduce new material.
- **Erratum:** Document that contains only grammatical corrections to, or corrections of errors introduced during the publishing process of, an existing IEEE standard.

# Who participates in standards development?

- Stakeholders and interested parties
  - Individuals
  - Industry/Companies
  - Government/Federal agencies
  - Public
- Open in membership, participation and governance
- No restrictions – any individual or company



<http://www.standardsuniversity.org/>



# Standards Resources

- IEEE-SA Standards Development Cycle - <http://standards.ieee.org/develop/index.html>
  - Overview of process, procedures
- Standards Status Report - <http://standards.ieee.org/develop/project/status.html>
  - Search for standards and drafts to find the status and description
- Approved Standards - <http://standards.ieee.org/about/sba/index.html>
  - Listing of IEEE-SA Standard Board approvals
- Global Cooperation - <http://standards.ieee.org/develop/intl/index.html>
  - IEEE-SA supports collaboration, development and adoption of standards across the globe in partnership with industry, governments and the public (e.g., ISO, IEC, ITU)
- eTools - <https://development.standards.ieee.org/my-site>
  - IEEE-SA's collection of online tools and resources for standards developers





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# Why Publish with the IEEE?

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Publishing  
creates value

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for your institution

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for your faculty

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for your investors  
and donors

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for science & technology

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for students

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# What else increases an IEEE author's visibility?

IEEE's relationships with indexing and abstracting providers



THOMSON REUTERS



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Publish

# IEEE journal or IEEE conference?

- A **journal article** is a fully developed presentation of your work and its final findings
  - Original research results presented
  - Clear conclusions are made and supported by the data
- A **conference article** can be written while research is ongoing
  - Can present preliminary results or highlight recent work
  - Gain informal feedback to use in your research
- Conference articles are typically shorter than journal articles, with less detail and fewer references

Publish

# IEEE journal or IEEE conference?

## IEEE Journals



- IEEE journals are cited 3 times more often in patent applications than other leading publisher's journals



- A high percentage of articles submitted to any professional publication are rejected

## IEEE Conferences

- IEEE Conference proceedings are recognized worldwide as the most vital collection of consolidated published articles in EE, computer science, related fields
- Per IEEE Policy, if you do not present your article at a conference, it may be suppressed in IEEE *Xplore* and not indexed in other databases



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## Aims & Scope

The theory, design and application of Control Systems. It shall encompass components, and the integration of these components, as are necessary for the construction of such systems. The word 'systems' as used herein shall be interpreted to include physical, biological, organizational and other entities and combinations thereof, which can be represented through a mathematical symbolism. The Field of Interest: shall include scientific, technical, industrial or other activities that contribute to this field, or utilize the techniques or products of this field, subject, as the art develops, to additions, subtractions, or other modifications directed or approved by the IEEE Technical Activities Board.

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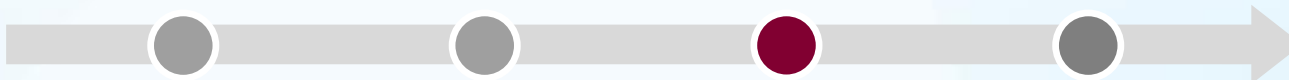
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# Paper Structure

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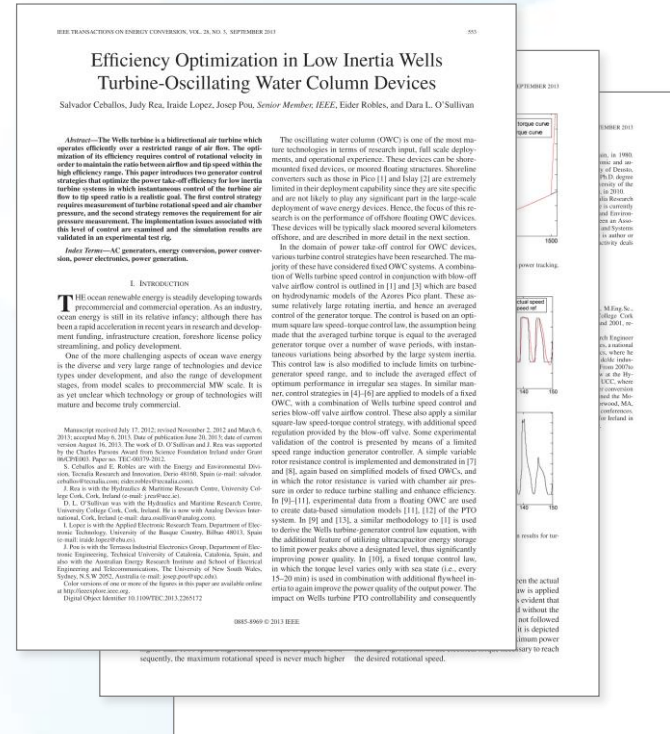
Introduction

Methodology

Results/Discussions/Findings

Conclusion

References



# Paper Structure

## Title

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- Answer the reader's question:  
*"Is this article relevant to me?"*
- Grab the reader's attention
- Describe the content of a paper using the fewest possible words
  - Is crisp, concise
  - Uses keywords
  - Avoids jargon

Good  
Title

VS.

Bad  
Title

Paper Structure

# Good vs. Bad Title

*A Human Expert-based Approach to Electrical Peak Demand Management*

**VS**

*A better approach of managing environmental and energy sustainability via a study of different methods of electric load forecasting*



Paper Structure

# Good vs. Better Title

An Investigation into the Effects of Residential Air-Conditioning Maintenance in Reducing the Demand for Electrical Energy

**VS**

*"Role of Air-Conditioning Maintenance on Electric Power Demand"*

# Paper Structure

## Abstract

A “stand alone” condensed version of the article

- No more than 250 words; written in the past tense
- Uses keywords and index terms

**What you did**

**Why you did**

**Why they're useful & important & move the field forward**

**How the results were useful, important & move the field forward**

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# Good vs. Bad Abstract

The objective of this paper was to propose a human expert-based approach to electrical peak demand management. The proposed approach helped to allocate demand curtailments (MW) among distribution substations (DS) or feeders in an electric utility service area based on requirements of the central load dispatch center. Demand curtailment allocation was quantified taking into account demand response (DR) potential and load curtailment priority of each DS, which can be determined using DS loading level, capacity of each DS, customer types (residential/commercial) and load categories (deployable, interruptible or critical). Analytic Hierarchy Process (AHP) was used to model a complex decision-making process according to both expert inputs and objective parameters. Simulation case studies were conducted to demonstrate how the proposed approach can be implemented to perform DR using real-world data from an electric utility. Simulation results demonstrated that the proposed approach is capable of achieving realistic demand curtailment allocations among different DSs to meet the peak load reduction requirements at the utility level.

## Vs

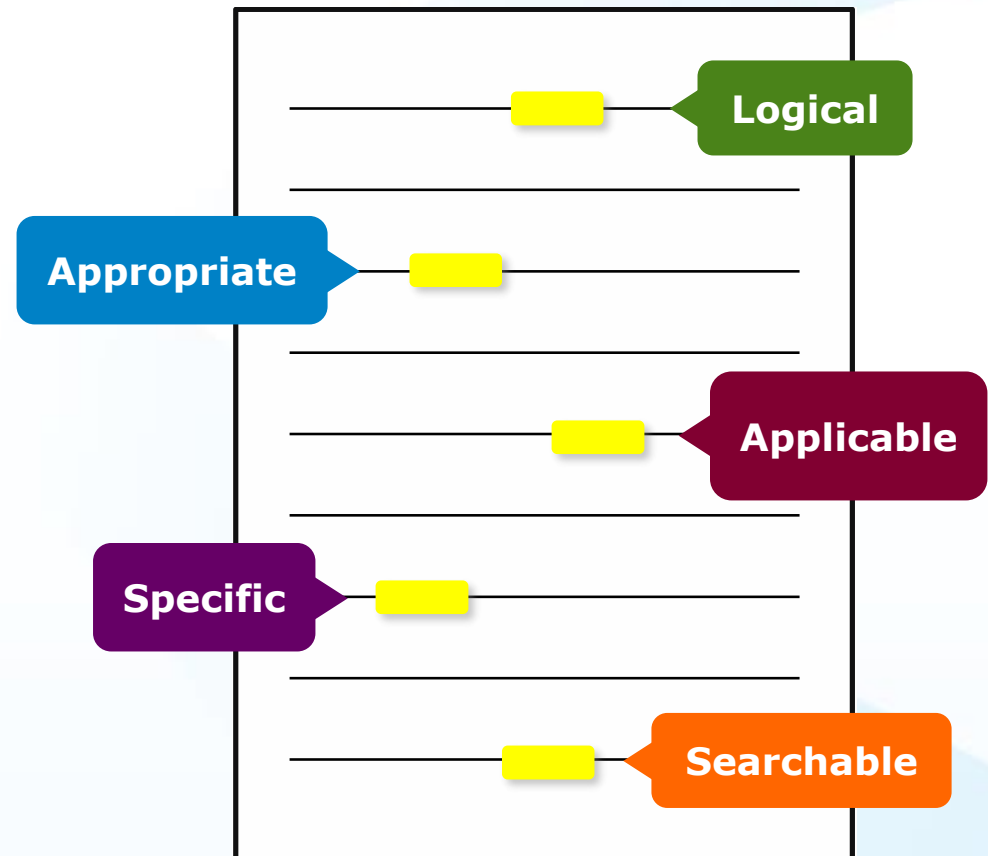
This paper presents and assesses a framework for an engineering capstone design program. **We explain** how student preparation, project selection, and instructor mentorship are the three key elements that must be addressed before the capstone experience is ready for the students. **Next, we describe** a way to administer and execute the capstone design experience including design workshops and lead engineers. **We describe the importance** in assessing the capstone design experience and report recent assessment results of our framework. **We comment** specifically on what students thought were the most important aspects of their experience in engineering capstone design and provide quantitative insight into what parts of the framework are most important.

*First person, present tense*

*No actual results, only describes the organization of the paper*

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Use in the Title and  
Abstract for enhanced  
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## IEEE Keywords

Bit rate, Decoding, Encoding, Parallel processing, Video coding

## Authors Keywords

High Efficiency Video Coding (HEVC), parallel programming, video coding

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### **INSPEC: Non-Controlled Indexing**

12-core system, H.264-advanced video coding, HEVC parallelization approaches, OWF, WPP, frequency 3.33 GHz, high efficiency video coding, overlapped wavefront, parallel efficiency, parallel friendliness, parallel scalability, parallelization proposals, tiles, wavefront parallel processing

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# Paper Structure

## Introduction

- A description of the problem you researched
- It should move step by step through, should be written in present tense:

Generally known information about the topic

Prior studies' historical context to your research

Your hypothesis and an overview of the results

How the article is organized

- The introduction should **not be**
  - Too broad or vague
  - More than 2 pages



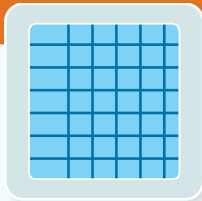
# Paper Structure

## Methodology

- Problem formulation and the processes used to solve the problem, prove or disprove the hypothesis
- Use illustrations to clarify ideas, support conclusions:

### Tables

Present representative data or when exact values are important to show



### Figures

Quickly show ideas/conclusions that would require detailed explanations



### Graphs

Show relationships between data points or trends in data



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## ■ ***Tables***

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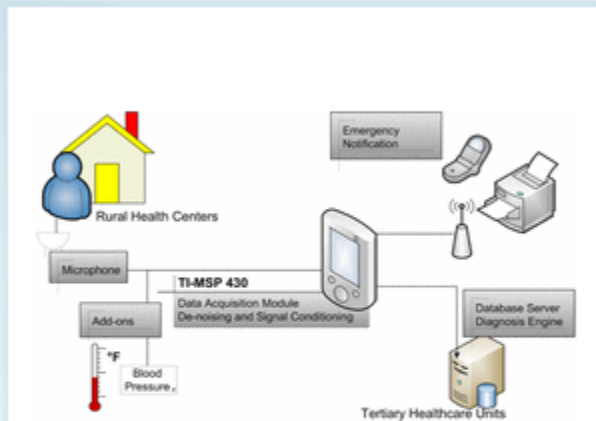


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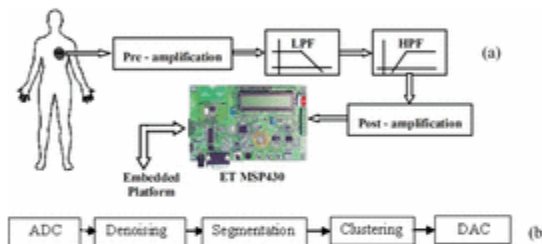


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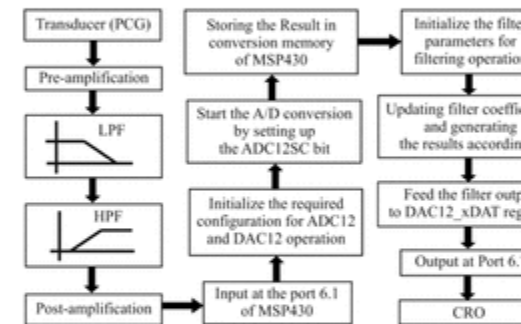
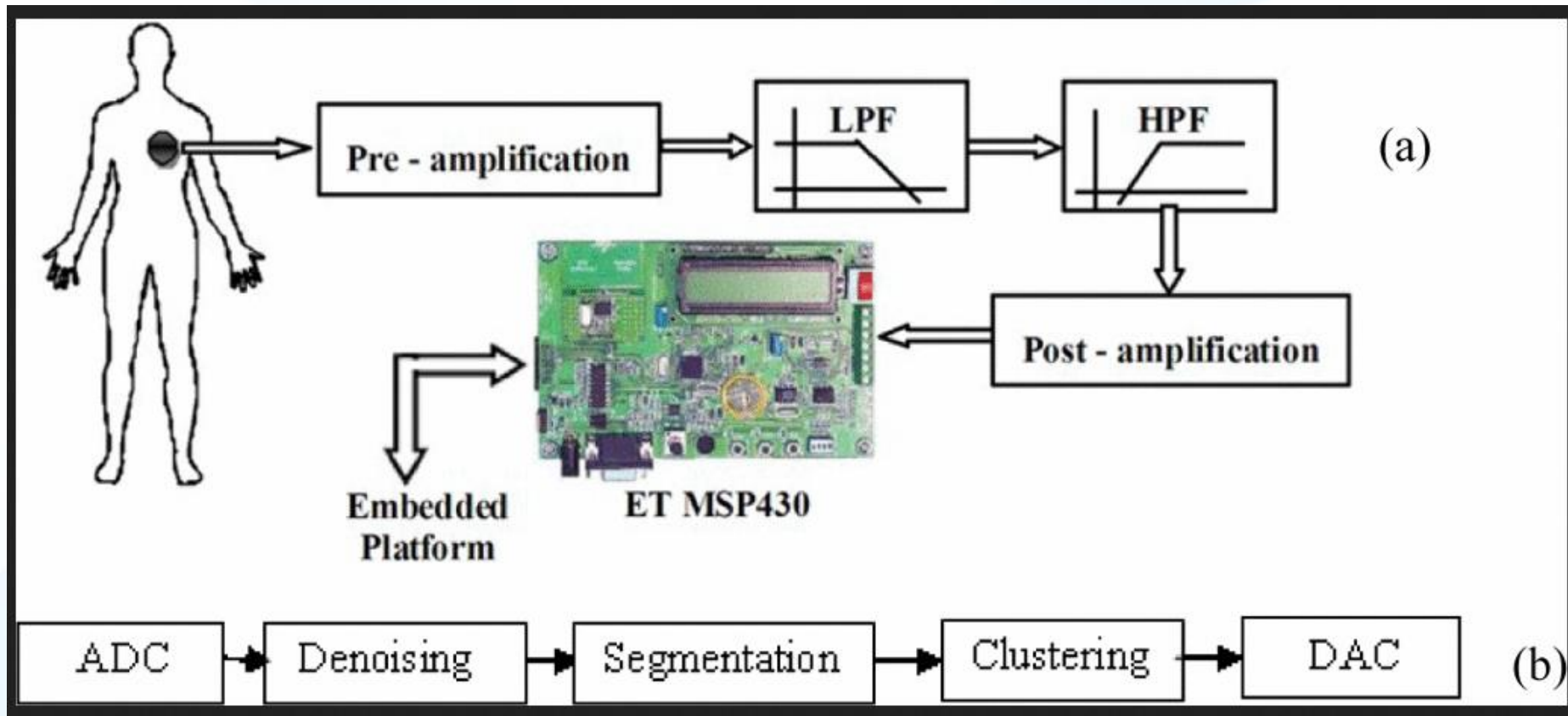


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# Paper Structure

# Results/discussion

Demonstrate that you solved the problem or made significant advances

## Results: Summarized Data

- Should be clear and concise
- Use figures or tables with narrative to illustrate findings

## Discussion: Interprets the Results

- Why your research offers a new solution
- Acknowledge any limitations

## Discussion

## Results

the SC algorithm over the whole range of  $w$  values increase to 3–4 K, except for the TIGR<sub>1+11</sub> database, with an RMSE of 2 K. This last result is explained by the  $w$  distribution, which is biased toward low values of  $w$  in this database. When only atmospheric profiles with  $w$  values lower than  $3 \text{ g} \cdot \text{cm}^{-2}$  are selected, the SC algorithm provides RMSEs around 1.5 K, with almost equal values of bias and standard deviation, around 1 K in both cases (with a negative bias, thus the SC underestimates the LST). In contrast, when only  $w$  values higher than  $3 \text{ g} \cdot \text{cm}^{-2}$  are considered, the SC algorithm provides RMSEs higher than 5 K. In these cases, it is preferable to calculate the atmospheric functions of the SC algorithm directly from (3) rather than approximating them by a polynomial fit approach as given by (4).

### V. DISCUSSION AND CONCLUSION

The two Landsat-8 TIR bands allow the intercomparison of two LST retrieval methods based on different physical assumptions, such as the SC (only one TIR band required) algorithms (two TIR bands required). Direct inversion of the transfer equation, which can be considered a “ground-truth” algorithm, is assumed to be a “ground-truth” algorithm in the sense that the information about the surface and  $L_d$  is accurate enough. The SC algorithm in this letter is a combination of the previous SC algorithm developed for Landsat-4 and Landsat-5 TM sensors, and the ETM+ sensor on board the Landsat-7 platform [9], and it could be used to generate consistent LST products from the historical Landsat data using a single algorithm. An advantage of the SC algorithm is that, apart from surface emissivity, only water vapor content is required as input. However, it is expected that errors on LST become unacceptable for high water vapor contents (e.g.,  $> 3 \text{ g} \cdot \text{cm}^{-2}$ ). This problem can be partly solved by computing the atmospheric functions directly from  $\tau$ ,  $L_d$ , and  $L_g$  values (see [5]), or also by including air temperature as input [15]. A main advantage of the SW algorithm is that it performs well over global conditions and, thus, a wide range of water vapor values; and that it only requires water vapor as input (apart from surface emissivity at the two TIR bands). However, the SW algorithm can be only applied to the new Landsat-8 TIRS data, since previous TM/ETM sensors only had one TIR band.

The LST algorithms presented in this letter were tested with simulated data sets obtained for a variety of global atmospheric conditions and surface emissivities. The results showed RMSE values of typically less than 1.5 K, although for the SC algorithm, this accuracy is only achieved for  $w$  values below  $3 \text{ g} \cdot \text{cm}^{-2}$ . Algorithm testing also showed that the SW errors are lower than the SC errors for increasing water vapor, and vice versa, as demonstrated in the simulation study presented in Sobrino and Jimenez-Munoz [18]. Although an extensive validation exercise from *in situ* measurements is required to assess the performance of the two LST algorithms, the results obtained for the simulated data, the sensitivity analysis, as well as the previous findings for algorithms with the same mathematical structure give confidence in the algorithm accuracies estimated here.

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# Paper Structure

## Conclusion

- Explain what the research has achieved
  - As it relates to the problem stated in the Introduction
  - Revisit the key points in each section
  - Include a summary of the main findings, important conclusions and implications for the field
- Provide benefits and shortcomings of:
  - The solution presented
  - Your research and methodology
- Suggest future areas for research



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We then have

$$\begin{aligned} (P_1^{n+} + P_1^{n-})^2 - (P_1^{n+} - P_1^{n-})^2 + 4P_1^{n+}P_1^{n-} \\ < (P_1^{n+} - P_1^{n-})^2 + 4P_1^{n+}P_1^{n-} \\ - (P_1^{n+} + P_1^{n-})^2 \end{aligned} \quad (32)$$

Since  $P_1^{n+} - P_1^{n-} = P_1^{n+} - P_1^{n-}$ , we then have  $P_1^{n+} < P_1^{n+}$ , and  $P_1^{n-} < P_1^{n-}$ . Because the operational cost is an increasing function of  $\{P_1^{n+}, P_1^{n-}\}$ , we obtain that

$$c_{opt}(P_1^{n+}, P_1^{n-}) < c_{opt}(P_1^{n+}, P_1^{n-}). \quad (33)$$

Therefore the optimal pair  $\{P_1^{n+}, P_1^{n-}\}$  must satisfy that  $P_1^{n+}P_1^{n-} = 0$ , i.e., only one of  $P_1^{n+}, P_1^{n-}$  can be non-zero. ■

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Peng Yang (S'11) received the B.Sc. degree in electrical engineering from University of Science and Technology, Anhui, China in 2009, and the M.Sc. and Ph.D. degrees in electrical engineering from Washington University in St. Louis, St. Louis, MO, USA, in 2011 and 2014, respectively. His Ph.D. advisor is Dr. Arya Nehorai. His research interests include statistical signal processing, optimization, machine learning, and compressive sensing, with applications to smart grids.



Arya Nehorai (S'80-M'83-SM'90-F'94) received the B.Sc. and M.Sc. degrees from the Weizmann Institute, Israel, and the Ph.D. degree from Stanford University, Stanford, CA, USA. He is the Eugene and Martha Lehman Professor and Chair of the Preston M. Green Department of Electrical and Systems Engineering (ESE) at Washington University in St. Louis (WUSTL), St. Louis, MO, USA. Earlier, he was a faculty member at Yale University and the University of Illinois at Chicago. Dr. Nehorai served as Editor-in-Chief of IEEE TRANSACTIONS ON SIGNAL PROCESSING from 2000 to 2002. From 2003 to 2005 he was the Vice President of the IEEE Signal Processing Society (SPS), the Chair of the Publications Board, and a member of the Executive Committee of this Society. He was the founding Editor of the special column on Leadership Reflections in IEEE Signal Processing Magazine from 2003 to 2006. He has been a Fellow of the IEEE since 1994, the Royal Statistical Society since 1996, and the AAAS since 2012.



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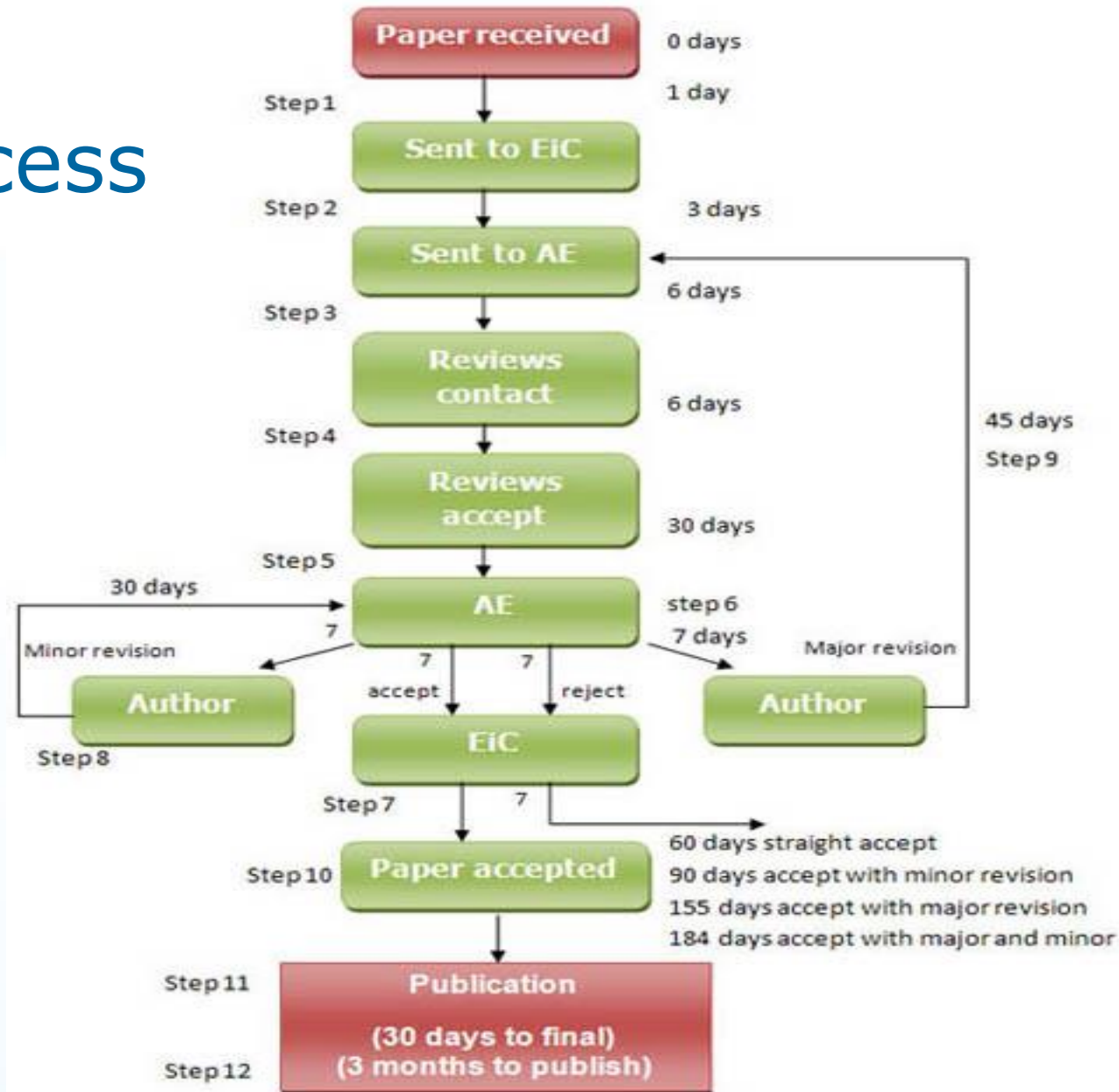
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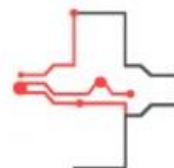


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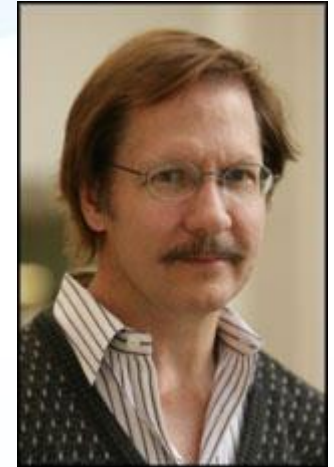
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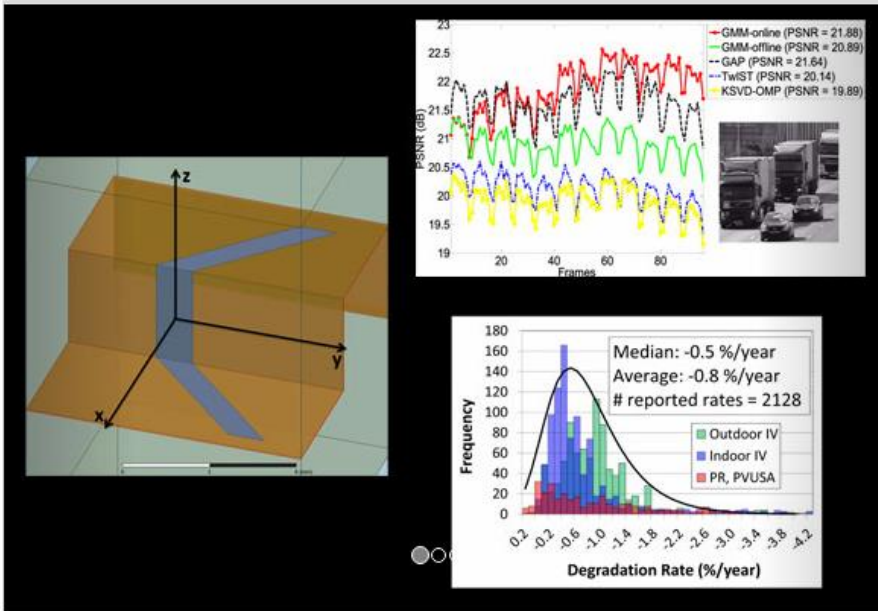
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
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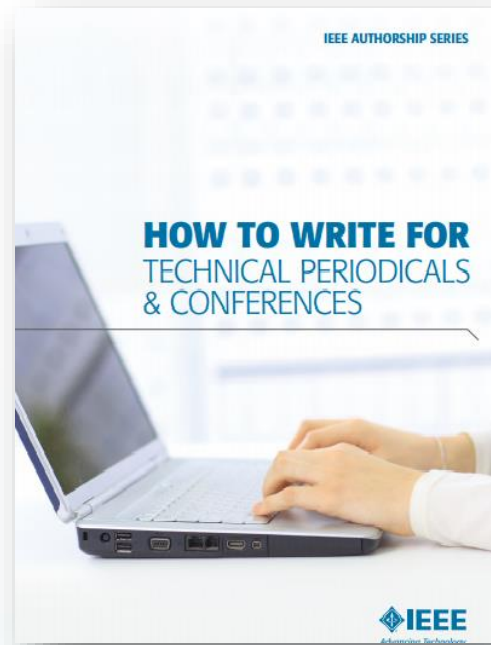
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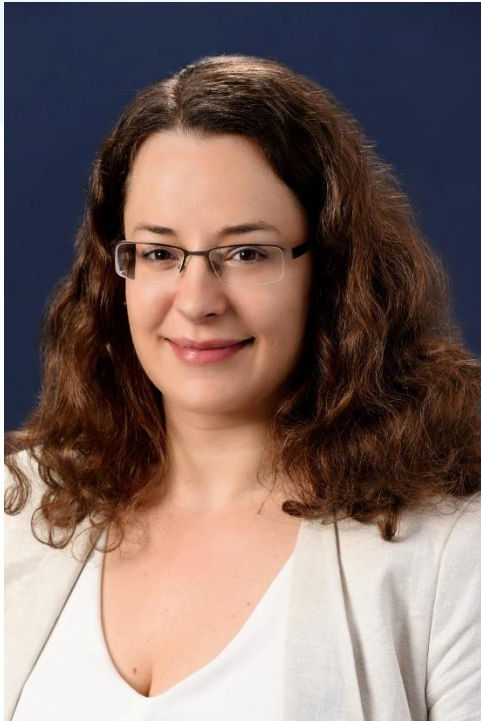
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- ❖ Web: [www.ieee.org/go/clientservices](http://www.ieee.org/go/clientservices)
- ❖ +49 30 44319367 Office in Berlin
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